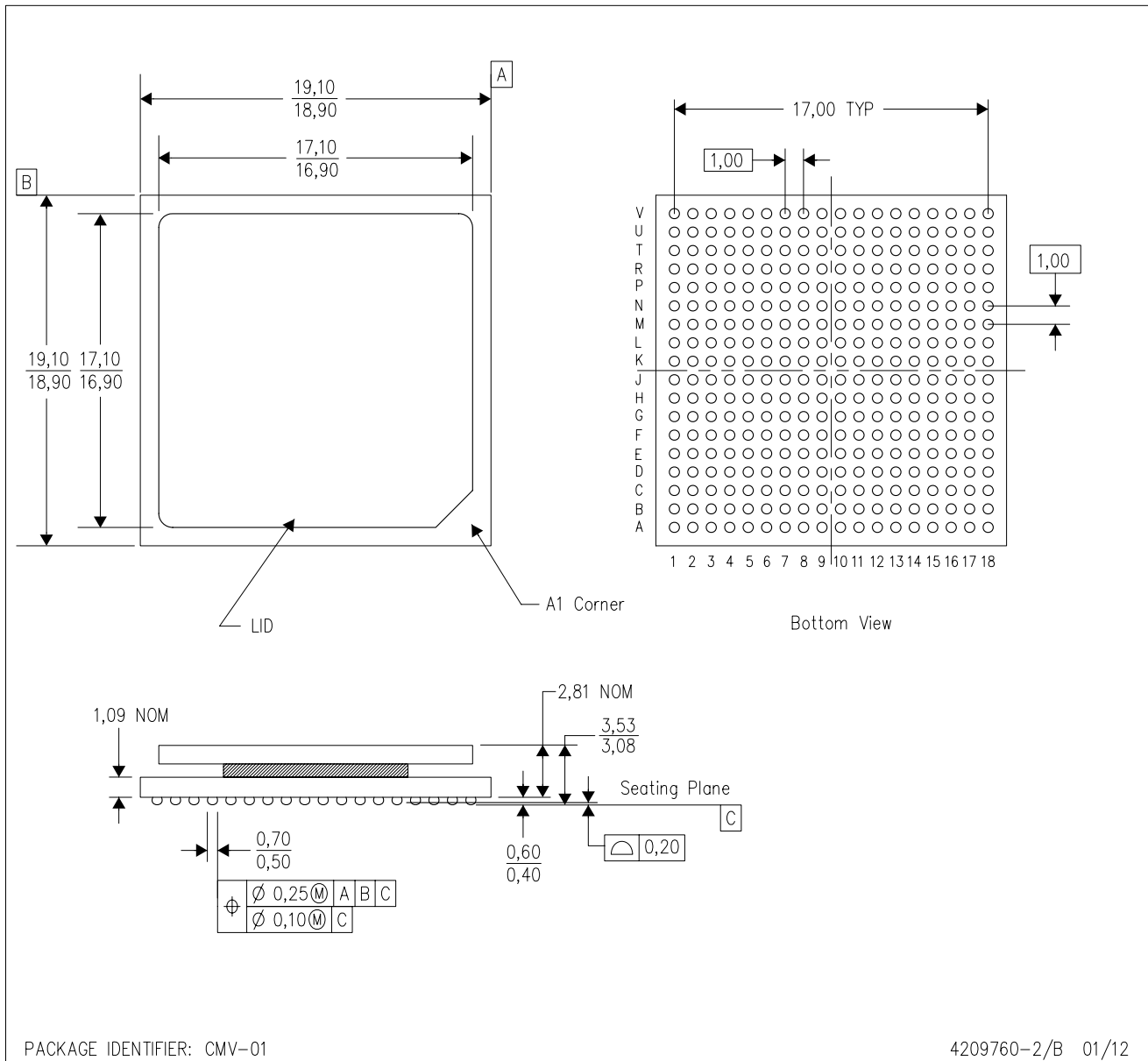


CMV (S-PBGA-N324)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Thermally enhanced plastic package with heat slug (HSL).
 - D. Flip chip application only.
 - E. Pb-free die bump and solder ball.

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